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Product Change Notification - JAON-29UFUC479　(Printer Friendly)

Date:	11 Jan 2016
Notification subject:	CCB 1753 Final Notice: Qualification of palladium coated copper (PdCu) bond wire for selected products fabricated at X-Fab available in 8L SOIC package at MTAI assembly site.
Notification text:	**PCN Status:** Final notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper (PdCu) bond wire for selected products fabricated at X-Fab available in 8L SOIC package at MTAI assembly site.

Pre Change:
Gold wire (Au) bond wire

Post Change:
Palladium coated copper (PdCu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	MTAI assembly site	MTAI Assembly site
Wire material	Au wire	PdCu Wire
Die attach material	8390A	8390A
Molding compound material	G600IMP10 / G600V / SG-8300GM	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:
None

Reason for Change:
To improve on-time delivery performance by qualifying Palladium coated copper (PdCu) bond wire

Change Implementation Status:
In Progress

Estimated First Ship Date:
February 8, 2016 (date code: 1606)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	October 2015				November 2015				December 2015					January 2016				February 2016			
WW	41	42	43	44	45	46	47	48	49	50	51	52	53	01	02	03	04	05	06	07	08
Initial PCN Issue Date		X																			
Qual Report Availability								X													
Final PCN Issue Date															X						
Implementation Date																			X		

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
October 13, 2015: Issued initial notification.
January 11, 2016: Issued final notification. Attached the qualification report. Revised the estimated first ship date from November 30, 2015 to February 8, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):   PCN_JAON-29UFUC479_Qual_Report.pdf
PCN_JAON-29UFUC479_Affected_CPN.pdf
PCN_JAON-29UFUC479_Affected_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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